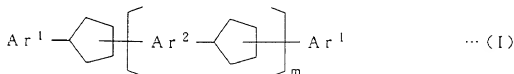


# ABSTRACT

This invention provides, as a novel compound suited as an encapsulating material for electronic devices, having a high Tg, being low moisture-absorptive, having a high adhesion and being rich in fluidity, a cyclopentylene compound represented by Formula (I) and its intermediate cyclopentenyl compound represented by Formula (III). In the formula, m is 0 or more, Ar<sup>1</sup> and Ar<sup>2</sup> are each a phenol residual group, a naphthol residual group or a fluorene derivative residual group, and each contain a hydroxyl group or a glycidyloxy group.



This invention also provides a resin composition and a molding material which contain the cyclopentylene compound of Formula (I), and an electronic device encapsulated with the molding material.